

cont'd
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wherein the carrier is for electrically coupling the semiconductor die to a circuit substrate, and wherein the carrier further comprises a die attach region, and wherein the plurality of bumps are arranged around the die attached region.

9. (Amended) A carrier for a semiconductor die package, the carrier comprising:

- (a) a metal layer; and
- (b) a plurality of bumps formed in the metal layer,

wherein the carrier is for electrically coupling the semiconductor die to a circuit substrate, and wherein each bump has a conical shape.

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10. (Amended) A semiconductor die package comprising:

- (a) a carrier comprising a metal layer, a die attach region, and a plurality of bumps formed in the metal layer; and
- (b) a semiconductor die electrically coupled to the die attach region of the carrier, and wherein the plurality of bumps are stamped bumps and are arranged around the die attach region, and wherein each of the bumps has a height that is greater than or equal to a thickness of the semiconductor die.

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24. (Amended) A method for forming a carrier for a semiconductor die package, the method comprising:

- (a) providing a metal layer; and
- (b) forming a plurality of bumps in the metal layer, wherein the formed bumps are capable of being electrically coupled to conductive regions of a circuit substrate, and wherein forming the plurality of bumps comprises stamping.

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29. (New) The method of claim 24 wherein the bumps each have a conical shape.